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Dimensions

Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	SMD Comm X8R HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	30 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	16 VDC
Dielectric Withstanding Voltage	40 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MHz 1.0Vrms
Dissipation Factor	2.5% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms